What is claimed is:

1. A method of cutting an article from a substrate, comprising:

focusing a pulsed laser beam into a laser beam focal line;

directing the laser beam focal line into the substrate at a first plurality of locations along a first predetermined path, the laser beam focal line generating an induced absorption within the substrate that produces a defect line within the substrate along the laser beam focal line at each location of the first plurality of locations, wherein the first predetermined path is a closed path;

heating the substrate along the first predetermined path to propagate a crack through each defect line of the first plurality of locations, thereby isolating an interior plug from the substrate; and

heating the interior plug after the isolating to remove the plug from the substrate.

2. The method according to claim 1, further comprising directing the laser beam focal line into the substrate at a second plurality of locations along a second predetermined path not intersecting the first predetermined path, the laser beam focal line generating an induced absorption within the substrate that produces a defect line along the laser beam focal line within the substrate at each location of the second plurality of locations.

3. The method according to claim 2, further comprising heating the substrate along the second predetermined path to propagate a crack through each defect line of the second plurality of locations.

4. The method according to claim 2, wherein the first predetermined path is a circular path and the second predetermined path is a circular path concentric with the first predetermined path.

5. The method according to claim 1, wherein heating the substrate along the first predetermined path comprises traversing a second laser beam over the first predetermined path.

6. The method according to claim 1, wherein the plug deforms during heating of the plug.

7. The method according to claim 1, wherein at least a portion of the plug is heated to a temperature equal to or greater than a softening temperature of the substrate.

8. The method according to claim 1, wherein the heating the plug heats only a central area of the plug

9. The method according to claim 1, wherein the interior plug drops from the substrate upon cooling without application of an external mechanical force to the interior plug.

10. A glass article made by the method according to any one of claims 1 to 9.